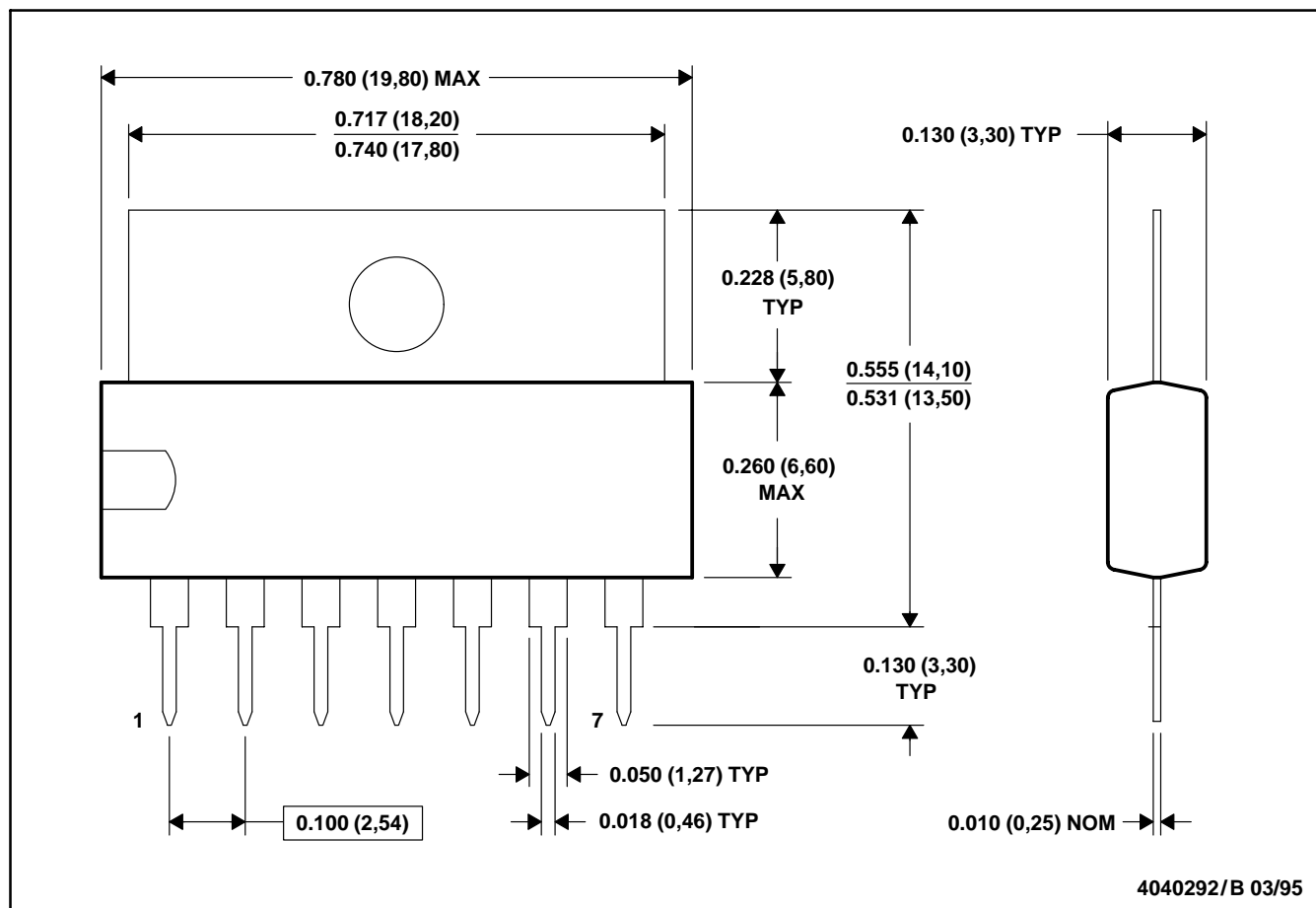


SK (R-PSIP-T7)

PLASTIC SINGLE-IN-LINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions include mold flash or protrusion.
 - Thermally enhanced molded plastic package with an exposed heat flange on top.



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